

# STTH6002C

### High efficiency ultrafast diode

#### Main product characteristics

I <sub>F(AV)</sub>	2 x 30 A
V <sub>RRM</sub>	200 V
T <sub>j</sub> (max)	175° C
V <sub>F</sub> (typ)	0.75 V
t <sub>rr</sub> (typ)	22 ns

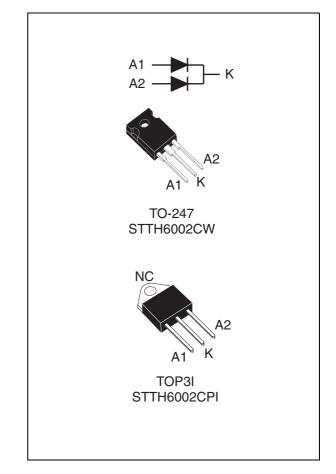
#### Features and benefits

- Suited for SMPS
- Low losses
- Low forward and reverse recovery times
- High surge current capability
- High junction temperature

#### Description

Dual center tab rectifier suited for switch mode power supplies and high frequency DC to DC converters.

Packaged in TO-247 and TOP3I, this device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection



#### **Order codes**

Part Number	Marking
STTH6002CW	STTH6002C
STTH6002CPI	STTH6002C

www.st.com

## 1 Characteristics

#### Table 1. Absolute ratings (limiting values at $T_j = 25^{\circ}$ C, unless otherwise specified)

Symbol	F	Value	Unit		
V <sub>RRM</sub>	Repetitive peak reverse voltage		200	V	
I <sub>F(RMS)</sub>	RMS forward current	50	Α		
	$I_{F(AV)}$ Average forward current, $\delta = 0.5$	TO-247	Per diode $T_c = 140^{\circ} C$	30	
		10-247	Per device $T_c = 125^{\circ} C$	60	•
<sup>I</sup> F(AV)		7000	Per diode $T_c = 120^\circ C$	30	A
		ТОРЗІ	Per device $T_c = 105^{\circ} C$	60	
I <sub>FSM</sub>	Surge non repetitive forward current	330	Α		
T <sub>stg</sub>	Storage temperature range	-65 to +175	°C		
Тj	Maximum operating junction tempera	175	°C		

#### Table 2.Thermal parameters

Symbol		Value	Unit		
		TO 047	Per diode	1.2	
Б	lupation to acco	TO-247	Total	0.8	
R <sub>th(j-c)</sub>	Junction to case	TODAL	Per diode	1.8	° C AAI
		ТОРЗІ		1.20	° C/W
D	Courting	TO-247		0.4	
Rth(c)	R <sub>th(c)</sub> Coupling	TOP3I		0.6	

When the two diodes 1 and 2 are used simultaneously:

 $\Delta Tj(diode \ 1) = P \ (diode \ 1) \ X \ R_{th(j-c)} \ (Per \ diode) + P \ (diode \ 2) \ x \ R_{th(c)}$ 



Symbol	Parameter	Test co	Тур	Max.	Unit	
I <sub>B</sub> <sup>(1)</sup>			V <sub>B</sub> = V <sub>BBM</sub>		30	
'R`´	IR <sup>(1)</sup> Reverse leakage current	$T_j = 125^\circ C$	VR − VRRM	30	300	μA
		T <sub>i</sub> = 25° C	I <sub>F</sub> = 30 A		1.05	
v (2)	V <sub>F</sub> <sup>(2)</sup> Forward voltage drop	$r_j = 25$ C	I <sub>F</sub> = 60 A		1.18	V
VF`'		T 150° C	I <sub>F</sub> = 30 A	0.75	0.84	V
		$T_j = 150^\circ C$	I <sub>F</sub> = 60 A	0.9	0.99	

Table 3. Static electrical characteristics

1. Pulse test:  $t_p = 5 \text{ ms}, \delta < 2 \%$ 

2. Pulse test:  $t_p$  = 380 µs,  $\delta$  < 2 %

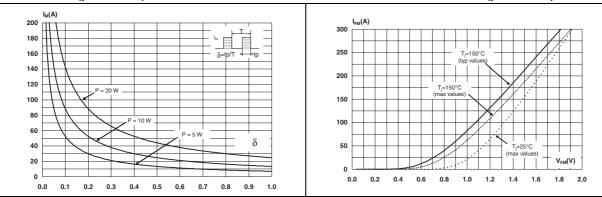
To evaluate the conduction losses use the following equation: P = 0.69 x  $I_{F(AV)}$  + 0.005  $I_{F}^{2}(RMS)$ 

Table 4. Dynamic characteristics

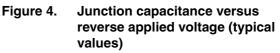
Symbol	Parameter	Test conditions	Тур	Max.	Unit
t <sub>rr</sub>	Reverse recovery time	$\label{eq:IF} \begin{array}{l} I_F = 1 \ A, \ dI_F/dt = 200 \ A/\mus, \\ V_R = 30 \ V, \ T_j = 25 \ ^\circC \end{array}$	22	27	ns
I <sub>RM</sub>	Reverse recovery current	$    I_F = 30 \text{ A, } dI_F/dt = 200 \text{ A}/\mu\text{s}, \\     V_R = 160 \text{ V, } T_j = 125 \text{ °C} $	7.6	9.5	А
t <sub>fr</sub>	Forward recovery time	$I_F = 30 \text{ A}, dI_F/dt = 200 \text{ A}/\mu \text{s}$ $V_{FR} = 1.1 \text{ x } V_{Fmax}, T_j = 25 \text{ °C}$		220	ns
V <sub>FP</sub>	Forward recovery voltage	$I_F = 30 \text{ A, } dI_F/dt = 200 \text{ A}/\mu\text{s},$ $T_j = 25 ^\circ\text{C}$	2.5		V

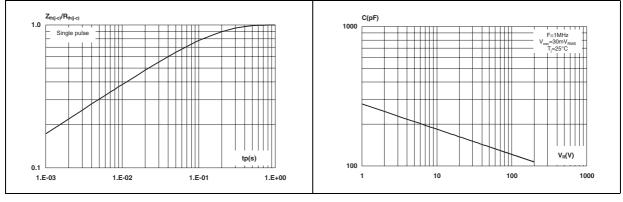
# Figure 1. Peak current versus duty cycle (per diode)

Figure 2. Forward voltage drop versus forward current (per diode)



# Figure 3. Relative variation of thermal impedance junction to case versus pulse duration





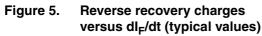


Figure 6. Reverse recovery time versus dl<sub>F</sub>/dt (typical values)

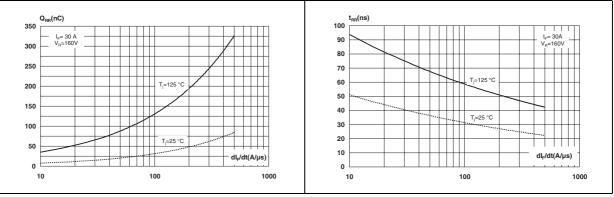
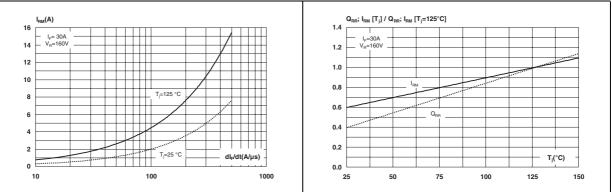


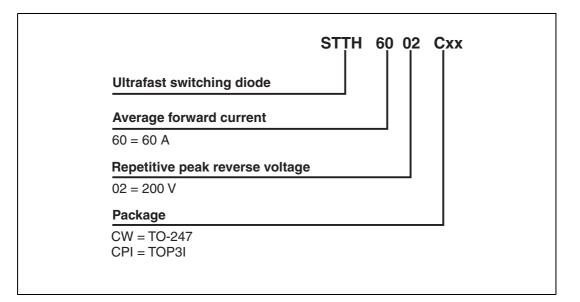
Figure 7. Peak reverse recovery current versus dl<sub>F</sub>/dt (typical values)

Figure 8. Dynamic parameters versus junction temperature





## 2 Ordering information scheme





## 3 Package information

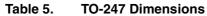
Epoxy meets UL94, V0

Cooling method: by conduction (C)

Recommended torque value: 0.8 Nm

Maximum torque value: 1.0 Nm

				DIMEN	SIONS		
	REF.	М	illimete	rs		Inches	
		Min.	Тур	Max.	Min.	Тур	Max.
		4.85		5.15	0.191		0.203
	D	2.20		2.60	0.086		0.102
V Aller I	Е	0.40		0.80	0.015		0.031
	F	1.00		1.40	0.039		0.055
	F1		3.00			0.118	
	F2		2.00			0.078	
	F3	2.00		2.40	0.078		0.094
	F4	3.00		3.40	0.118		0.133
	G		10.90			0.429	
	Н	15.45		15.75	0.608		0.620
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	L	19.85		20.15	0.781		0.793
$\begin{array}{c} & & \\$	L1	3.70		4.30	0.145		0.169
$ \begin{array}{c c} & & & \\ \hline \\ \hline$	L2		18.50			0.728	
	L3	14.20		14.80	0.559		0.582
	L4		34.60			1.362	
	L5		5.50			0.216	
	М	2.00		3.00	0.078		0.118
	V		5°			5°	
	V2		60°			60°	
	Dia.	3.55		3.65	0.139		0.143





	<u>.</u>			DIMEN	SIONS	
		REF	Millin	neters	Inc	hes
, н.,	Α.		Min.	Max.	Min.	Max.
		А	4.4	4.6	0.173	0.181
	⊢ B→+←	В	1.45	1.55	0.057	0.061
		С	14.35	15.60	0.565	0.614
		D	0.5	0.7	0.020	0.028
		Е	2.7	2.9	0.106	0.114
	F	15.8	16.5	0.622	0.650	
		G	20.4	21.1	0.815	0.831
		Н	15.1	15.5	0.594	0.610
$\downarrow \downarrow \downarrow \downarrow$		J	5.4	5.65	0.213	0.222
	К	3.4	3.65	0.134	0.144	
		ØL	4.08	4.17	0.161	0.164
		Р	1.20	1.40	0.047	0.055
		R	4.60	Тур.	0.181	Г Тур.

Table 6.TOP3I dimensions

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

## 4 Ordering information

Part Number	Marking	Package	Weight	Base qty	Delivery mode
STTH6002CW	STTH6002C	TO-247	4.46 g	30	Tube
STTH6002CPI	STTH6002C	TOP3I	4.7 g	30	Tube

## 5 Revision history

Date	Revision	Description of Changes
Feb-2004	1	First issue
05-Apr-2006	2	Reformatted to current template. Package TOP3I added.



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